

Purolite™
CriticalResin™
NRW5010XLC

聚苯乙烯 大孔, I型 强碱阴树脂, 氢氧
型, 高孔隙率, 超低氯化物, 核级

主要应用

- 阴离子覆层
- 一次冷却剂抛光
- 高硼锂冷却剂

产品优势

- 最小氯化物释放
- 极细胶体颗粒去除

* 12个月货架期

适用系统

- CVCS在线床

包装样式

- 1CF 纸盒
- 5 CF 纤维板桶

典型物理和化学参数

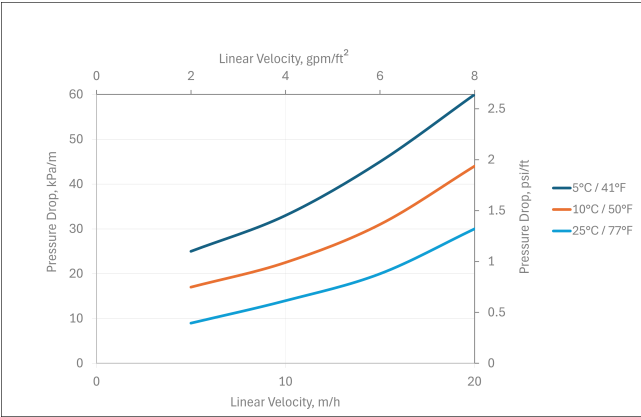
聚合物骨架	大孔型聚苯乙烯二乙烯苯交联
外观	球状颗粒
官能团	季铵I型
离子型态	OH- 型
全交换容量 (最小)	0.4 eq/L (8.7 Kgr/ft³) (OH- 型)
含水量	67 - 75 % (Cl⁻型)
粒径分布	425 - 1200 µm
< 425 µm (最大)	2 %
均一系数 (最大)	1.8
转型率 (最低)	95 % (OH- 型)
阴离子型, CO ₃ ²⁻ (最大)	5 %
阴离子型, SO ₄ ²⁻ (最大)	0.3 %
阴离子型, Cl⁻ (最大)	0.05 %
杂质 铁 (最大)	50 ppm
杂质 钠 (最大)	20 ppm
杂质 重金属 (最大)	30 ppm
包装密度 (大约)	590 - 630 g/L (36.9 - 39.4 lb/ft³)
温度限制, 不可再生床	100 °C (212.0 °F) (OH- 型)
温度限制, 可再生床	60 °C (140.0 °F) (OH- 型)
线速度	It is recommended not to exceed a linear flow of 20 m/h due to the special characteristics of the product.

水力学特性

压降

离子交换树脂的压降取决于粒度分布、床层高度、树脂颗粒间空隙体积，以及物料的流速和粘度。任何对这些参数的影响-比如被树脂床层截住的颗粒物、对树脂床层的异常压缩、床层的不规则分布-都会对压降产生不利影响，造成压头损失。针对不同的物料质量、应用环境和系统设计，流速可能处于10 – 40 BV/h范围内变化。

床层压降



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